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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	ARM® Cortex®-M0+
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I <sup>2</sup> C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LVD, POR, PWM, WDT
Number of I/O	41
Program Memory Size	16KB (16K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.71V ~ 3.6V
Data Converters	A/D 14x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/nxp-semiconductors/mkl05z16vlf4">https://www.e-xfl.com/product-detail/nxp-semiconductors/mkl05z16vlf4</a>

# 1 Ordering parts

## 1.1 Determining valid orderable parts

Valid orderable part numbers are provided on the web. To determine the orderable part numbers for this device, go to [www.freescale.com](http://www.freescale.com) and perform a part number search for the following device numbers: PKL05 and MKL05

# 2 Part identification

## 2.1 Description

Part numbers for the chip have fields that identify the specific part. You can use the values of these fields to determine the specific part you have received.

## 2.2 Format

Part numbers for this device have the following format:

Q KL## A FFF R T PP CC N

## 2.3 Fields

This table lists the possible values for each field in the part number (not all combinations are valid):

Field	Description	Values
Q	Qualification status	<ul style="list-style-type: none"> <li>M = Fully qualified, general market flow</li> <li>P = Prequalification</li> </ul>
KL##	Kinetis family	<ul style="list-style-type: none"> <li>KL05</li> </ul>
A	Key attribute	<ul style="list-style-type: none"> <li>Z = Cortex-M0+</li> </ul>
FFF	Program flash memory size	<ul style="list-style-type: none"> <li>8 = 8 KB</li> <li>16 = 16 KB</li> <li>32 = 32 KB</li> </ul>
R	Silicon revision	<ul style="list-style-type: none"> <li>(Blank) = Main</li> <li>A = Revision after main</li> </ul>

*Table continues on the next page...*

## 3.2 Definition: Operating behavior

An *operating behavior* is a specified value or range of values for a technical characteristic that are guaranteed during operation if you meet the operating requirements and any other specified conditions.

### 3.2.1 Example

This is an example of an operating behavior, which is guaranteed if you meet the accompanying operating requirements:

Symbol	Description	Min.	Max.	Unit
I <sub>WP</sub>	Digital I/O weak pullup/pulldown current	10	130	μA

## 3.3 Definition: Attribute

An *attribute* is a specified value or range of values for a technical characteristic that are guaranteed, regardless of whether you meet the operating requirements.

### 3.3.1 Example

This is an example of an attribute:

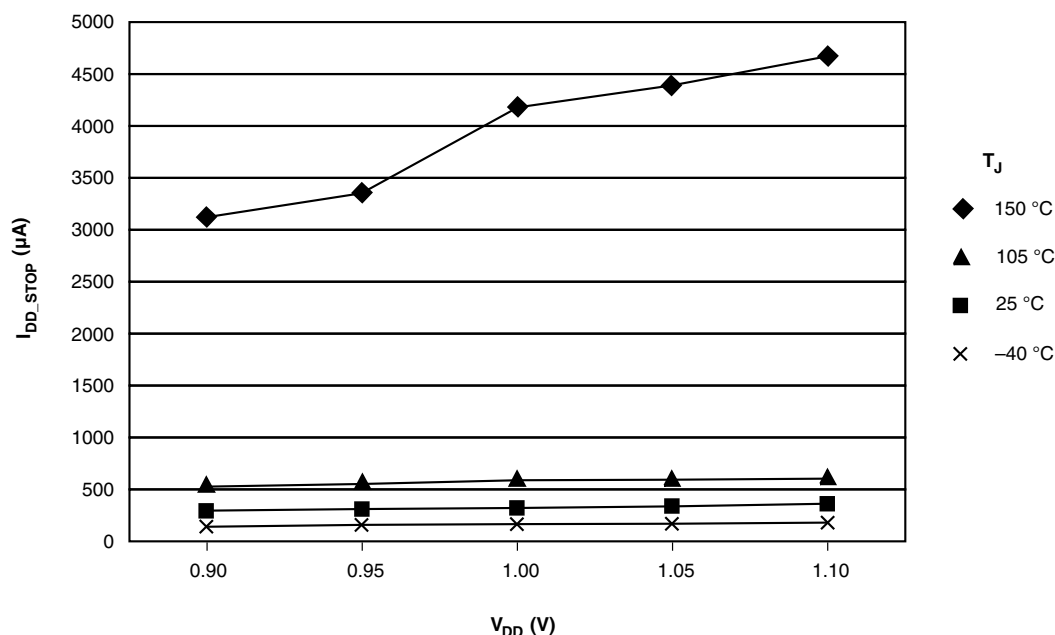
Symbol	Description	Min.	Max.	Unit
CIN_D	Input capacitance: digital pins	—	7	pF

## 3.4 Definition: Rating

A *rating* is a minimum or maximum value of a technical characteristic that, if exceeded, may cause permanent chip failure:

- *Operating ratings* apply during operation of the chip.
- *Handling ratings* apply when the chip is not powered.

## Ratings



## 3.9 Typical Value Conditions

Typical values assume you meet the following conditions (or other conditions as specified):

Symbol	Description	Value	Unit
T <sub>A</sub>	Ambient temperature	25	°C
V <sub>DD</sub>	3.3 V supply voltage	3.3	V

## 4 Ratings

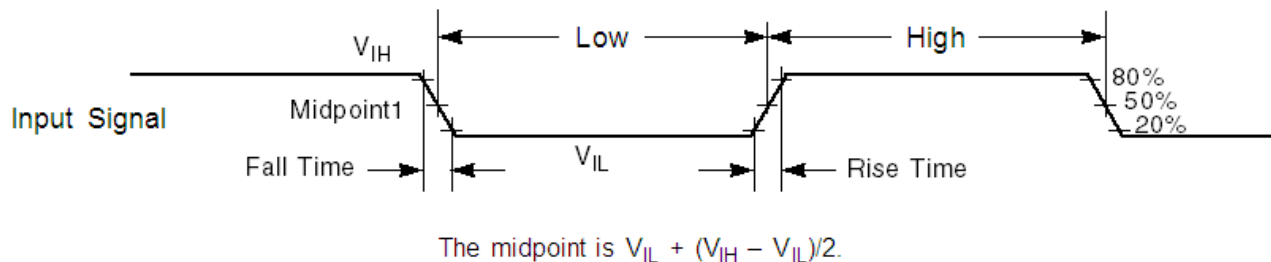
### 4.1 Thermal handling ratings

Symbol	Description	Min.	Max.	Unit	Notes
T <sub>STG</sub>	Storage temperature	-55	150	°C	1
T <sub>SDR</sub>	Solder temperature, lead-free	—	260	°C	2

1. Determined according to JEDEC Standard JESD22-A103, *High Temperature Storage Life*.
2. Determined according to IPC/JEDEC Standard J-STD-020, *Moisture/Reflow Sensitivity Classification for Nonhermetic Solid State Surface Mount Devices*.

## 5.1 AC electrical characteristics

Unless otherwise specified, propagation delays are measured from the 50% to the 50% point, and rise and fall times are measured at the 20% and 80% points, as shown in the following figure.



**Figure 1. Input signal measurement reference**

All digital I/O switching characteristics, unless otherwise specified, assume:

1. output pins
  - have  $C_L=30\text{pF}$  loads,
  - are slew rate disabled, and
  - are normal drive strength

## 5.2 Nonswitching electrical specifications

### 5.2.1 Voltage and current operating requirements

**Table 1. Voltage and current operating requirements**

Symbol	Description	Min.	Max.	Unit	Notes
$V_{DD}$	Supply voltage	1.71	3.6	V	
$V_{DDA}$	Analog supply voltage	1.71	3.6	V	
$V_{DD} - V_{DDA}$	$V_{DD}$ -to- $V_{DDA}$ differential voltage	-0.1	0.1	V	
$V_{SS} - V_{SSA}$	$V_{SS}$ -to- $V_{SSA}$ differential voltage	-0.1	0.1	V	
$V_{IH}$	Input high voltage <ul style="list-style-type: none"> <li>• <math>2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}</math></li> <li>• <math>1.7\text{ V} \leq V_{DD} \leq 2.7\text{ V}</math></li> </ul>	$0.7 \times V_{DD}$	—	V	
		$0.75 \times V_{DD}$	—	V	
$V_{IL}$	Input low voltage <ul style="list-style-type: none"> <li>• <math>2.7\text{ V} \leq V_{DD} \leq 3.6\text{ V}</math></li> <li>• <math>1.7\text{ V} \leq V_{DD} \leq 2.7\text{ V}</math></li> </ul>	—	$0.35 \times V_{DD}$	V	
		—	$0.3 \times V_{DD}$	V	
$V_{HYS}$	Input hysteresis	$0.06 \times V_{DD}$	—	V	

Table continues on the next page...

**Table 5. Power consumption operating behaviors (continued)**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
I <sub>DD_VLLS0</sub>	Very-low-leakage stop mode 0 current (SMC_STOPCTRL[PORPO] = 0) <ul style="list-style-type: none"> <li>at 3.0 V</li> <li>at 25 °C</li> <li>at 50 °C</li> <li>at 70 °C</li> <li>at 85 °C</li> <li>at 105 °C</li> </ul>				nA	
		—	449.6	959.2		
		—	1200	12155.08		
		—	2900	15323.29		
		—	5900	16384.55		
		—	14800	26773.45		
I <sub>DD_VLLS0</sub>	Very-low-leakage stop mode 0 current (SMC_STOPCTRL[PORPO] = 1) <ul style="list-style-type: none"> <li>at 3.0 V</li> <li>at 25 °C</li> <li>at 50 °C</li> <li>at 70 °C</li> <li>at 85 °C</li> <li>at 105 °C</li> </ul>				nA	5
		—	221.7	894.24		
		—	1000	3784.55		
		—	2600	12018.39		
		—	5600	18722.23		
		—	14400	24665.06		

1. The analog supply current is the sum of the active or disabled current for each of the analog modules on the device. See each module's specification for its supply current.
2. MCG configured for FEI mode.
3. Incremental current consumption from peripheral activity is not included.
4. MCG configured for BLPI mode.
5. No brownout

**Table 6. Low power mode peripheral adders — typical value**

Symbol	Description	Temperature (°C)						Unit
		-40	25	50	70	85	105	
I <sub>IREFSTEN4MHz</sub>	4 MHz internal reference clock (IRC) adder. Measured by entering STOP or VLPS mode with 4 MHz IRC enabled.	56	56	56	56	56	56	μA
I <sub>IREFSTEN32KHz</sub>	32 kHz internal reference clock (IRC) adder. Measured by entering STOP mode with the 32 kHz IRC enabled.	52	52	52	52	52	52	μA
I <sub>IREFSTEN4MHz</sub>	External 4 MHz crystal clock adder. Measured by entering STOP or VLPS mode with the crystal enabled.	206	228	237	245	251	258	uA

Table continues on the next page...

## 5.3 Switching specifications

### 5.3.1 Device clock specifications

Symbol	Description	Min.	Max.	Unit	Notes
Normal run mode					
f <sub>SYS</sub>	System and core clock	—	48	MHz	
f <sub>BUS</sub>	Bus clock	—	24	MHz	
f <sub>FLASH</sub>	Flash clock	—	24	MHz	
f <sub>LPTMR</sub>	LPTMR clock	—	24	MHz	
VLPR mode <sup>1</sup>					
f <sub>SYS</sub>	System and core clock	—	4	MHz	
f <sub>BUS</sub>	Bus clock	—	1	MHz	
f <sub>FLASH</sub>	Flash clock	—	1	MHz	
f <sub>LPTMR</sub>	LPTMR clock	—	24	MHz	
f <sub>ERCLK</sub>	External reference clock	—	16	MHz	
f <sub>LPTMR_pin</sub>	LPTMR clock	—	24	MHz	
f <sub>LPTMR_ERCLK</sub>	LPTMR external reference clock	—	16	MHz	
f <sub>osc_hi_2</sub>	Oscillator crystal or resonator frequency — high frequency mode (high range) (MCG_C2[RANGE]=1x)	—	16	MHz	
f <sub>TPM</sub>	TPM asynchronous clock	—	8	MHz	
f <sub>UART0</sub>	UART0 asynchronous clock	—	8	MHz	

1. The frequency limitations in VLPR mode here override any frequency specification listed in the timing specification for any other module.

### 5.3.2 General Switching Specifications

These general purpose specifications apply to all signals configured for GPIO, UART, and I<sup>2</sup>C signals.

Symbol	Description	Min.	Max.	Unit	Notes
	GPIO pin interrupt pulse width (digital glitch filter disabled) — Synchronous path	1.5	—	Bus clock cycles	1
	External RESET and NMI pin interrupt pulse width — Asynchronous path	100	—	ns	2
	GPIO pin interrupt pulse width — Asynchronous path	16	—	ns	2
	Port rise and fall time	—	36	ns	3

**Table 11. MCG specifications (continued)**

Symbol	Description		Min.	Typ.	Max.	Unit	Notes
$\Delta f_{\text{dco\_t}}$	Total deviation of trimmed average DCO output frequency over fixed voltage and temperature range of 0 - 70 °C		—	± 0.4	± 1.5	% $f_{\text{dco}}$	1, 2
$f_{\text{intf\_ft}}$	Internal reference frequency (fast clock) — factory trimmed at nominal $V_{\text{DD}}$ and 25 °C		—	4	—	MHz	
$\Delta f_{\text{intf\_ft}}$	Frequency deviation of internal reference clock (fast clock) over temperature and voltage — factory trimmed at nominal $V_{\text{DD}}$ and 25 °C		—	+1/-2	± 3	% $f_{\text{intf\_ft}}$	2
$f_{\text{intf\_t}}$	Internal reference frequency (fast clock) — user trimmed at nominal $V_{\text{DD}}$ and 25 °C		3	—	5	MHz	
$f_{\text{loc\_low}}$	Loss of external clock minimum frequency — RANGE = 00		(3/5) x $f_{\text{ints\_t}}$	—	—	kHz	
$f_{\text{loc\_high}}$	Loss of external clock minimum frequency — RANGE = 01, 10, or 11		(16/5) x $f_{\text{ints\_t}}$	—	—	kHz	
FLL							
$f_{\text{fll\_ref}}$	FLL reference frequency range		31.25	—	39.0625	kHz	
$f_{\text{dco}}$	DCO output frequency range	Low range (DRS = 00) $640 \times f_{\text{fll\_ref}}$	20	20.97	25	MHz	3, 4
		Mid range (DRS = 01) $1280 \times f_{\text{fll\_ref}}$	40	41.94	48	MHz	
$f_{\text{dco\_t\_DMX32}}$	DCO output frequency	Low range (DRS = 00) $732 \times f_{\text{fll\_ref}}$	—	23.99	—	MHz	5, 6
		Mid range (DRS = 01) $1464 \times f_{\text{fll\_ref}}$	—	47.97	—	MHz	
$J_{\text{cyc\_fll}}$	FLL period jitter • $f_{\text{VCO}} = 48 \text{ MHz}$		—	180	—	ps	7
$t_{\text{fll\_acquire}}$	FLL target frequency acquisition time		—	—	1	ms	8

1. This parameter is measured with the internal reference (slow clock) being used as a reference to the FLL (FEI clock mode).
2. The deviation is relative to the factory trimmed frequency at nominal  $V_{DD}$  and 25 °C,  $f_{ints\_ft}$ .
3. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32 = 0.
4. The resulting system clock frequencies must not exceed their maximum specified values. The DCO frequency deviation ( $\Delta f_{dco\_t}$ ) over voltage and temperature must be considered.
5. These typical values listed are with the slow internal reference clock (FEI) using factory trim and DMX32 = 1.
6. The resulting clock frequency must not exceed the maximum specified clock frequency of the device.
7. This specification is based on standard deviation (RMS) of period or frequency.
8. This specification applies to any time the FLL reference source or reference divider is changed, trim value is changed, DMX32 bit is changed, DRS bits are changed, or changing from FLL disabled (BLPE, BLPI) to FLL enabled (FEI, FEE, FBE, FBI). If a crystal/resonator is being used as the reference, this specification assumes it is already running.

## 6.3.2 Oscillator electrical specifications

This section provides the electrical characteristics of the module.



**Table 12. Oscillator DC electrical specifications (continued)**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$V_{pp}^5$	Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, low-power mode (HGO=0)	—	0.6	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — low-frequency, high-gain mode (HGO=1)	—	$V_{DD}$	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, low-power mode (HGO=0)	—	0.6	—	V	
	Peak-to-peak amplitude of oscillation (oscillator mode) — high-frequency, high-gain mode (HGO=1)	—	$V_{DD}$	—	V	

1.  $V_{DD}=3.3$  V, Temperature =25 °C
2. See crystal or resonator manufacturer's recommendation
3.  $C_x, C_y$  can be provided by using the integrated capacitors when the low frequency oscillator (RANGE = 00) is used. For all other cases external capacitors must be used.
4. When low power mode is selected,  $R_F$  is integrated and must not be attached externally.
5. The EXTAL and XTAL pins should only be connected to required oscillator components and must not be connected to any other devices.

### 6.3.2.2 Oscillator frequency specifications

**Table 13. Oscillator frequency specifications**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$f_{osc\_lo}$	Oscillator crystal or resonator frequency — low frequency mode (MCG_C2[RANGE]=00)	32	—	40	kHz	
$f_{osc\_hi\_1}$	Oscillator crystal or resonator frequency — high frequency mode (low range) (MCG_C2[RANGE]=01)	3	—	8	MHz	
$f_{osc\_hi\_2}$	Oscillator crystal or resonator frequency — high frequency mode (high range) (MCG_C2[RANGE]=1x)	8	—	32	MHz	
$f_{ec\_extal}$	Input clock frequency (external clock mode)	—	—	48	MHz	1, 2
$t_{dc\_extal}$	Input clock duty cycle (external clock mode)	40	50	60	%	
$t_{cst}$	Crystal startup time — 32 kHz low-frequency, low-power mode (HGO=0)	—	—	—	ms	3, 4
	Crystal startup time — 32 kHz low-frequency, high-gain mode (HGO=1)	—	—	—	ms	
	Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), low-power mode (HGO=0)	—	0.6	—	ms	
	Crystal startup time — 8 MHz high-frequency (MCG_C2[RANGE]=01), high-gain mode (HGO=1)	—	1	—	ms	

1. Other frequency limits may apply when external clock is being used as a reference for the FLL or PLL.
2. When transitioning from FBE to FEI mode, restrict the frequency of the input clock so that, when it is divided by FRDIV, it remains within the limits of the DCO input clock frequency.

2. Maximum times for erase parameters based on expectations at cycling end-of-life.

### 6.4.1.3 Flash high voltage current behaviors

Table 16. Flash high voltage current behaviors

Symbol	Description	Min.	Typ.	Max.	Unit
I <sub>DD_PGM</sub>	Average current adder during high voltage flash programming operation	—	2.5	6.0	mA
I <sub>DD_ERS</sub>	Average current adder during high voltage flash erase operation	—	1.5	4.0	mA

### 6.4.1.4 Reliability specifications

Table 17. NVM reliability specifications

Symbol	Description	Min.	Typ. <sup>1</sup>	Max.	Unit	Notes
Program Flash						
t <sub>nvmretp10k</sub>	Data retention after up to 10 K cycles	5	50	—	years	
t <sub>nvmretp1k</sub>	Data retention after up to 1 K cycles	20	100	—	years	
n <sub>nvmcycp</sub>	Cycling endurance	10 K	50 K	—	cycles	2

1. Typical data retention values are based on measured response accelerated at high temperature and derated to a constant 25°C use profile. Engineering Bulletin EB618 does not apply to this technology. Typical endurance defined in Engineering Bulletin EB619.
2. Cycling endurance represents number of program/erase cycles at  $-40^{\circ}\text{C} \leq T_j \leq 125^{\circ}\text{C}$ .

## 6.5 Security and integrity modules

There are no specifications necessary for the device's security and integrity modules.

## 6.6 Analog

### 6.6.1 ADC electrical specifications

All ADC channels meet the 12-bit single-ended accuracy specifications.

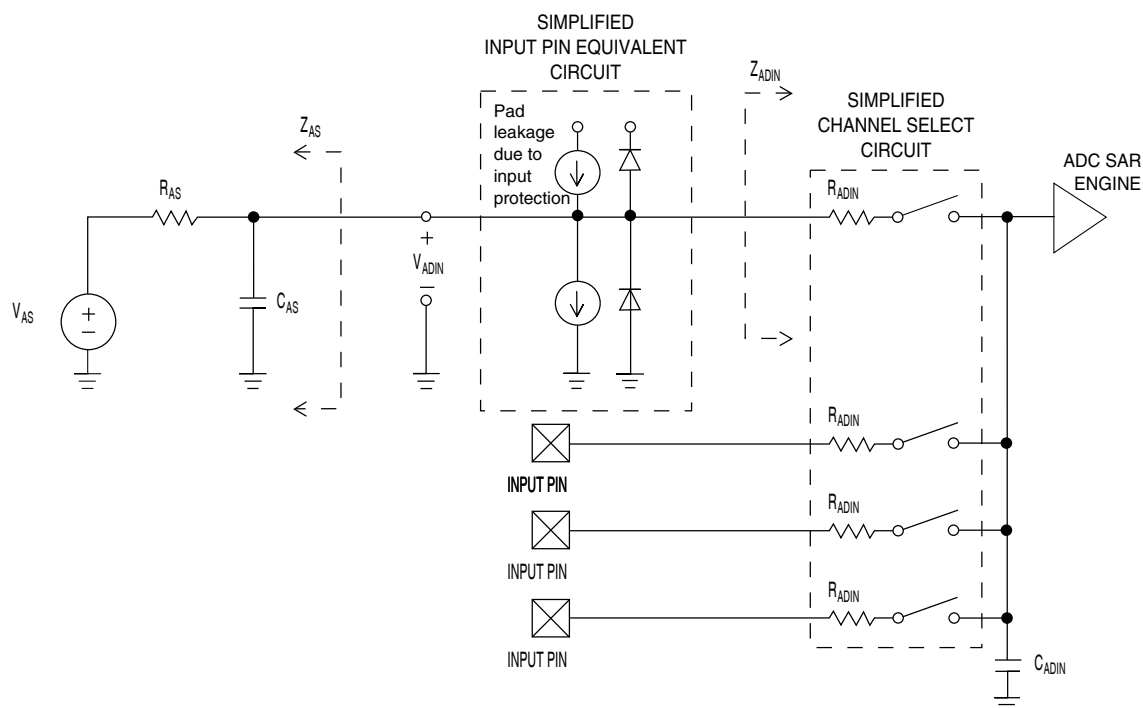


Figure 6. ADC input impedance equivalency diagram

### 6.6.1.2 12-bit ADC electrical characteristics

Table 19. 12-bit ADC characteristics ( $V_{REFH} = V_{DDA}$ ,  $V_{REFL} = V_{SSA}$ )

Symbol	Description	Conditions <sup>1</sup>	Min.	Typ. <sup>2</sup>	Max.	Unit	Notes
$I_{DDA\_ADC}$	Supply current		0.215	—	1.7	mA	3
$f_{ADACK}$	ADC asynchronous clock source	<ul style="list-style-type: none"> <li>ADLPC = 1, ADHSC = 0</li> <li>ADLPC = 1, ADHSC = 1</li> <li>ADLPC = 0, ADHSC = 0</li> <li>ADLPC = 0, ADHSC = 1</li> </ul>	1.2 2.4 3.0 4.4	2.4 4.0 5.2 6.2	3.9 6.1 7.3 9.5	MHz MHz MHz MHz	$t_{ADACK} = 1/f_{ADACK}$
	Sample Time	See Reference Manual chapter for sample times					
TUE	Total unadjusted error	<ul style="list-style-type: none"> <li>12-bit modes</li> <li>&lt;12-bit modes</li> </ul>	— —	±4 ±1.4	±6.8 ±2.1	LSB <sup>4</sup>	5
DNL	Differential non-linearity	<ul style="list-style-type: none"> <li>12-bit modes</li> <li>&lt;12-bit modes</li> </ul>	— —	±0.7 ±0.2	-1.1 to +1.9 -0.3 to 0.5	LSB <sup>4</sup>	5
INL	Integral non-linearity	<ul style="list-style-type: none"> <li>12-bit modes</li> <li>&lt;12-bit modes</li> </ul>	— —	±1.0 ±0.5	-2.7 to +1.9 -0.7 to +0.5	LSB <sup>4</sup>	5
$E_{FS}$	Full-scale error	<ul style="list-style-type: none"> <li>12-bit modes</li> <li>&lt;12-bit modes</li> </ul>	— —	-4 -1.4	-5.4 -1.8	LSB <sup>4</sup>	$V_{ADIN} = V_{DDA}$ 5

Table continues on the next page...

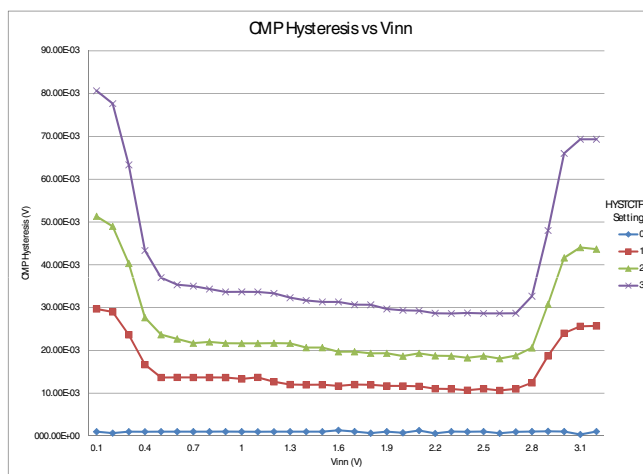


Figure 8. Typical hysteresis vs. Vin level ( $V_{DD} = 3.3\text{ V}$ ,  $\text{PMODE} = 0$ )

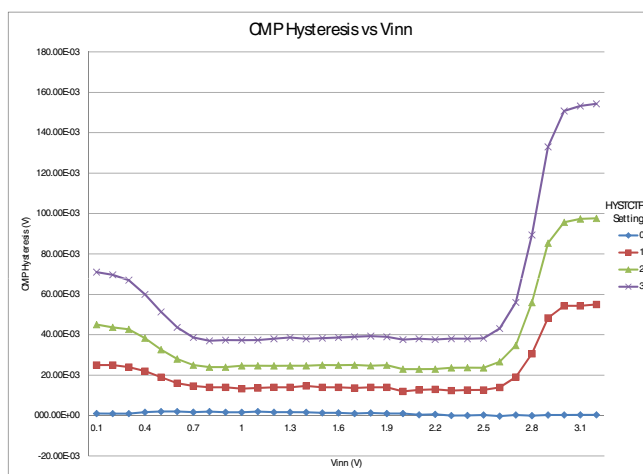


Figure 9. Typical hysteresis vs. Vin level ( $V_{DD} = 3.3\text{ V}$ ,  $\text{PMODE} = 1$ )

## 6.6.3 12-bit DAC electrical characteristics

### 6.6.3.1 12-bit DAC operating requirements

Table 21. 12-bit DAC operating requirements

Symbol	Description	Min.	Max.	Unit	Notes
$V_{DDA}$	Supply voltage		3.6	V	
$V_{DACR}$	Reference voltage	1.13	3.6	V	1
$T_A$	Temperature	Operating temperature range of the device		°C	
$C_L$	Output load capacitance	—	100	pF	2
$I_L$	Output load current	—	1	mA	

1. The DAC reference can be selected to be  $V_{DDA}$  or the voltage output of the VREF module (VREF\_OUT)
2. A small load capacitance (47 pF) can improve the bandwidth performance of the DAC

### 6.6.3.2 12-bit DAC operating behaviors

**Table 22. 12-bit DAC operating behaviors**

Symbol	Description	Min.	Typ.	Max.	Unit	Notes
$I_{DDA\_DACLP}$	Supply current — low-power mode	—	—	250	$\mu A$	
$I_{DDA\_DACHP}$	Supply current — high-speed mode	—	—	900	$\mu A$	
$t_{DACLP}$	Full-scale settling time (0x080 to 0xF7F) — low-power mode	—	100	200	$\mu s$	1
$t_{DACHP}$	Full-scale settling time (0x080 to 0xF7F) — high-power mode	—	15	30	$\mu s$	1
$t_{CCDACLP}$	Code-to-code settling time (0xBF8 to 0xC08) — low-power mode and high-speed mode	—	0.7	1	$\mu s$	1
$V_{dacoutl}$	DAC output voltage range low — high-speed mode, no load, DAC set to 0x000	—	—	100	mV	
$V_{dacouth}$	DAC output voltage range high — high-speed mode, no load, DAC set to 0xFFF	$V_{DACR} - 100$	—	$V_{DACR}$	mV	
INL	Integral non-linearity error — high speed mode	—	—	$\pm 8$	LSB	2
DNL	Differential non-linearity error — $V_{DACR} > 2 V$	—	—	$\pm 1$	LSB	3
DNL	Differential non-linearity error — $V_{DACR} = V_{REF\_OUT}$	—	—	$\pm 1$	LSB	4
$V_{OFFSET}$	Offset error	—	$\pm 0.4$	$\pm 0.8$	%FSR	5
$E_G$	Gain error	—	$\pm 0.1$	$\pm 0.6$	%FSR	5
PSRR	Power supply rejection ratio, $V_{DDA} \geq 2.4 V$	60	—	90	dB	
$T_{CO}$	Temperature coefficient offset voltage	—	3.7	—	$\mu V/C$	6
$T_{GE}$	Temperature coefficient gain error	—	0.000421	—	%FSR/C	
Rop	Output resistance load = 3 k $\Omega$	—	—	250	$\Omega$	
SR	Slew rate -80h → F7Fh → 80h <ul style="list-style-type: none"> <li>High power (SP<sub>HP</sub>)</li> <li>Low power (SP<sub>LP</sub>)</li> </ul>	1.2 0.05	1.7 0.12	— —	V/ $\mu s$	
BW	3dB bandwidth <ul style="list-style-type: none"> <li>High power (SP<sub>HP</sub>)</li> <li>Low power (SP<sub>LP</sub>)</li> </ul>	550 40	— —	— —	kHz	

- Settling within  $\pm 1$  LSB
- The INL is measured for 0 + 100 mV to  $V_{DACR} - 100$  mV
- The DNL is measured for 0 + 100 mV to  $V_{DACR} - 100$  mV
- The DNL is measured for 0 + 100 mV to  $V_{DACR} - 100$  mV with  $V_{DDA} > 2.4 V$
- Calculated by a best fit curve from  $V_{SS} + 100$  mV to  $V_{DACR} - 100$  mV
- $V_{DDA} = 3.0 V$ , reference select set for  $V_{DDA}$  (DACx\_CO:DACRFS = 1), high power mode (DACx\_CO:LPEN = 0), DAC set to 0x800, temperature range is across the full range of the device

## Peripheral operating requirements and behaviors

All timing is shown with respect to 20%  $V_{DD}$  and 80%  $V_{DD}$  thresholds, unless noted, as well as input signal transitions of 3 ns and a 30 pF maximum load on all SPI pins.

**Table 23. SPI master mode timing on slew rate disabled pads**

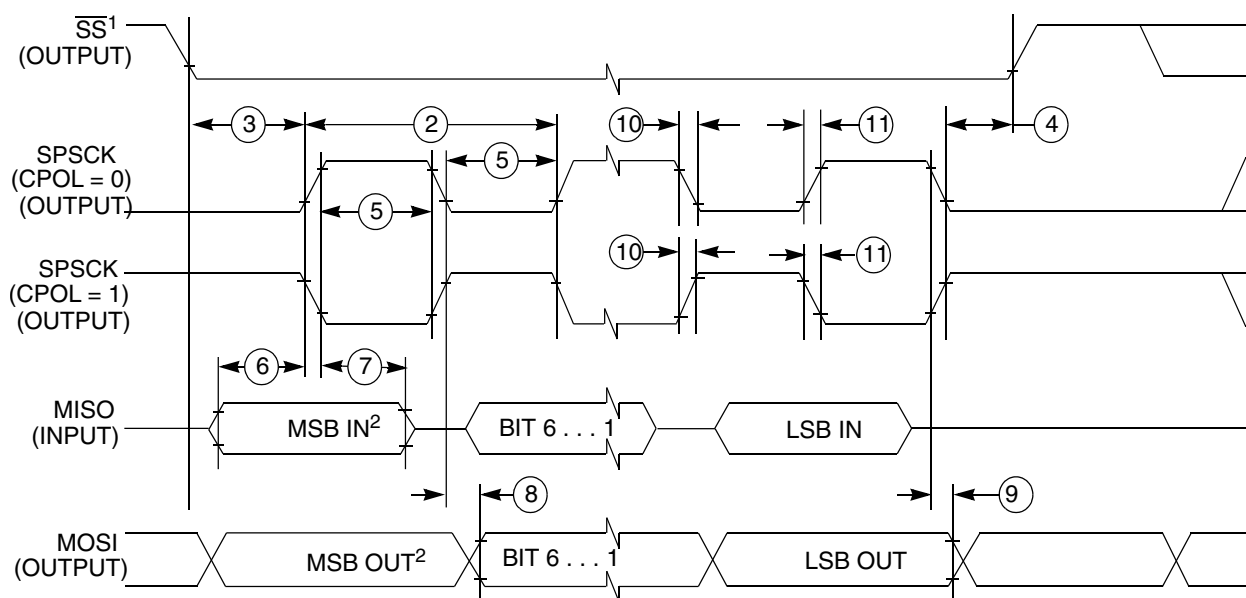
Num.	Symbol	Description	Min.	Max.	Unit	Note
1	$f_{op}$	Frequency of operation	$f_{periph}/2048$	$f_{periph}/2$	Hz	1
2	$t_{SPSCK}$	SPSCK period	$2 \times t_{periph}$	$2048 \times t_{periph}$	ns	2
3	$t_{Lead}$	Enable lead time	1/2	—	$t_{SPSCK}$	—
4	$t_{Lag}$	Enable lag time	1/2	—	$t_{SPSCK}$	—
5	$t_{WSPSCK}$	Clock (SPSCK) high or low time	$t_{periph} - 30$	$1024 \times t_{periph}$	ns	—
6	$t_{SU}$	Data setup time (inputs)	16	—	ns	—
7	$t_{HI}$	Data hold time (inputs)	0	—	ns	—
8	$t_v$	Data valid (after SPSCK edge)	—	10	ns	—
9	$t_{HO}$	Data hold time (outputs)	0	—	ns	—
10	$t_{RI}$	Rise time input	—	$t_{periph} - 25$	ns	—
	$t_{FI}$	Fall time input				
11	$t_{RO}$	Rise time output	—	25	ns	—
	$t_{FO}$	Fall time output				

1. For SPI0  $f_{periph}$  is the bus clock ( $f_{BUS}$ ).
2.  $t_{periph} = 1/f_{periph}$

**Table 24. SPI master mode timing on slew rate enabled pads**

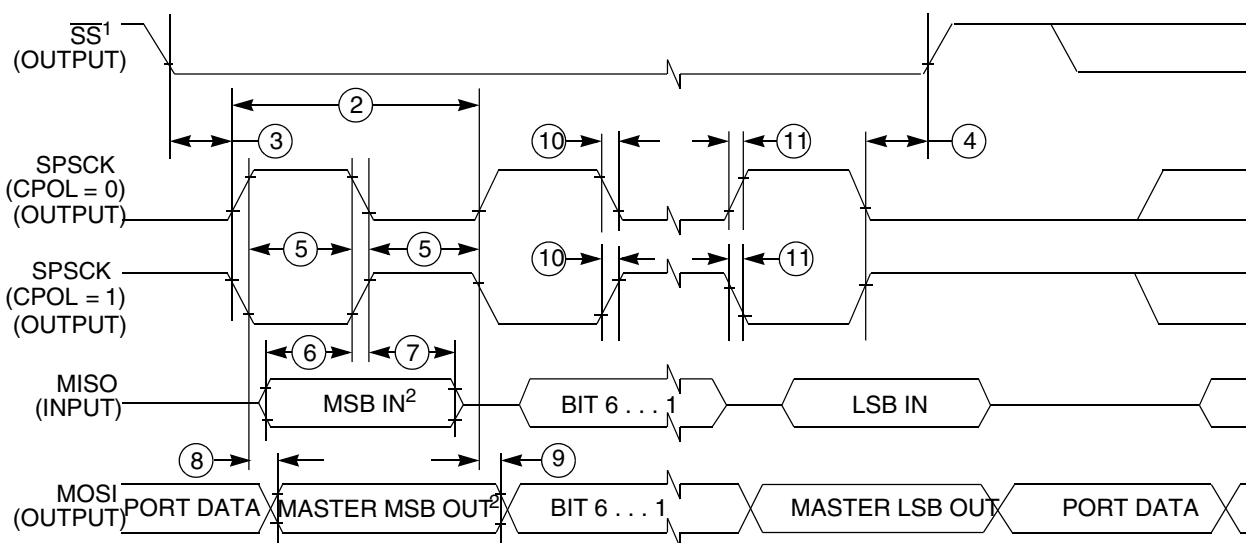
Num.	Symbol	Description	Min.	Max.	Unit	Note
1	$f_{op}$	Frequency of operation	$f_{periph}/2048$	$f_{periph}/2$	Hz	1
2	$t_{SPSCK}$	SPSCK period	$2 \times t_{periph}$	$2048 \times t_{periph}$	ns	2
3	$t_{Lead}$	Enable lead time	1/2	—	$t_{SPSCK}$	—
4	$t_{Lag}$	Enable lag time	1/2	—	$t_{SPSCK}$	—
5	$t_{WSPSCK}$	Clock (SPSCK) high or low time	$t_{periph} - 30$	$1024 \times t_{periph}$	ns	—
6	$t_{SU}$	Data setup time (inputs)	96	—	ns	—
7	$t_{HI}$	Data hold time (inputs)	0	—	ns	—
8	$t_v$	Data valid (after SPSCK edge)	—	52	ns	—
9	$t_{HO}$	Data hold time (outputs)	0	—	ns	—
10	$t_{RI}$	Rise time input	—	$t_{periph} - 25$	ns	—
	$t_{FI}$	Fall time input				
11	$t_{RO}$	Rise time output	—	36	ns	—
	$t_{FO}$	Fall time output				

1. For SPI0  $f_{periph}$  is the bus clock ( $f_{BUS}$ ).
2.  $t_{periph} = 1/f_{periph}$



1. If configured as an output.
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

**Figure 12. SPI master mode timing (CPHA = 0)**



1. If configured as output
2. LSBF = 0. For LSBF = 1, bit order is LSB, bit 1, ..., bit 6, MSB.

**Figure 13. SPI master mode timing (CPHA = 1)**

**Table 25. SPI slave mode timing on slew rate disabled pads**

Num.	Symbol	Description	Min.	Max.	Unit	Note
1	$f_{op}$	Frequency of operation	0	$f_{periph}/4$	Hz	1
2	$t_{SPSCCK}$	SPSCCK period	$4 \times t_{periph}$	—	ns	2
3	$t_{Lead}$	Enable lead time	1	—	$t_{periph}$	—
4	$t_{Lag}$	Enable lag time	1	—	$t_{periph}$	—
5	$t_{WSPSCCK}$	Clock (SPSCCK) high or low time	$t_{periph} - 30$	—	ns	—

Table continues on the next page...

**Table 25. SPI slave mode timing on slew rate disabled pads (continued)**

Num.	Symbol	Description	Min.	Max.	Unit	Note
6	$t_{SU}$	Data setup time (inputs)	2	—	ns	—
7	$t_{HI}$	Data hold time (inputs)	7	—	ns	—
8	$t_a$	Slave access time	—	$t_{periph}$	ns	3
9	$t_{dis}$	Slave MISO disable time	—	$t_{periph}$	ns	4
10	$t_v$	Data valid (after SPSCCK edge)	—	22	ns	—
11	$t_{HO}$	Data hold time (outputs)	0	—	ns	—
12	$t_{RI}$	Rise time input	—	$t_{periph} - 25$	ns	—
	$t_{FI}$	Fall time input				
13	$t_{RO}$	Rise time output	—	25	ns	—
	$t_{FO}$	Fall time output				

1. For SPI0  $f_{periph}$  is the bus clock ( $f_{BUS}$ ).
2.  $t_{periph} = 1/f_{periph}$
3. Time to data active from high-impedance state
4. Hold time to high-impedance state

**Table 26. SPI slave mode timing on slew rate enabled pads**

Num.	Symbol	Description	Min.	Max.	Unit	Note
1	$f_{op}$	Frequency of operation	0	$f_{periph}/4$	Hz	1
2	$t_{SPSCCK}$	SPSCCK period	$4 \times t_{periph}$	—	ns	2
3	$t_{Lead}$	Enable lead time	1	—	$t_{periph}$	—
4	$t_{Lag}$	Enable lag time	1	—	$t_{periph}$	—
5	$t_{WSPSCCK}$	Clock (SPSCCK) high or low time	$t_{periph} - 30$	—	ns	—
6	$t_{SU}$	Data setup time (inputs)	2	—	ns	—
7	$t_{HI}$	Data hold time (inputs)	7	—	ns	—
8	$t_a$	Slave access time	—	$t_{periph}$	ns	3
9	$t_{dis}$	Slave MISO disable time	—	$t_{periph}$	ns	4
10	$t_v$	Data valid (after SPSCCK edge)	—	122	ns	—
11	$t_{HO}$	Data hold time (outputs)	0	—	ns	—
12	$t_{RI}$	Rise time input	—	$t_{periph} - 25$	ns	—
	$t_{FI}$	Fall time input				
13	$t_{RO}$	Rise time output	—	36	ns	—
	$t_{FO}$	Fall time output				

1. For SPI0  $f_{periph}$  is the bus clock ( $f_{BUS}$ ).
2.  $t_{periph} = 1/f_{periph}$
3. Time to data active from high-impedance state
4. Hold time to high-impedance state



## 6.9 Human-machine interfaces (HMI)

### 6.9.1 TSI electrical specifications

**Table 27. TSI electrical specifications**

Symbol	Description	Min.	Type	Max	Unit
TSI_RUNF	Fixed power consumption in run mode	—	100	—	μA
TSI_RUNV	Variable power consumption in run mode (depends on oscillator's current selection)	1.0	—	128	μA
TSI_EN	Power consumption in enable mode	—	100	—	μA
TSI_DIS	Power consumption in disable mode	—	1.2	—	μA
TSI_TEN	TSI analog enable time	—	66	—	μs
TSI_CREF	TSI reference capacitor	—	1.0	—	pF
TSI_DVOLT	Voltage variation of VP & VM around nominal values	0.19	—	1.03	V

## 7 Dimensions

### 7.1 Obtaining package dimensions

Package dimensions are provided in package drawings.

To find a package drawing, go to [www.freescale.com](http://www.freescale.com) and perform a keyword search for the drawing's document number:

If you want the drawing for this package	Then use this document number
24-pin QFN	98ASA00474D
32-pin QFN	98ASA00473D
32-pin LQFP	98ASH70029A
48-pin LQFP	98ASH00962A

## 8 Pinout

## Pinout

48 LQFP	32 QFN	32 LQFP	24 QFN	Pin Name	Default	ALT0	ALT1	ALT2	ALT3
25	17	17	13	PTB1/ IRQ_9	ADC0_SE5/ TSIO_IN3/ DAC0_OUT/ CMP0_IN3	ADC0_SE5/ TSIO_IN3/ DAC0_OUT/ CMP0_IN3	PTB1/ IRQ_9	UART0_TX	UART0_RX
26	18	18	14	PTB2/ IRQ_10/ LLWU_P5	ADC0_SE4/ TSIO_IN2	ADC0_SE4/ TSIO_IN2	PTB2/ IRQ_10/ LLWU_P5	UART0_RX	UART0_TX
27	19	19	15	PTA8	ADC0_SE3/ TSIO_IN1	ADC0_SE3/ TSIO_IN1	PTA8		
28	20	20	16	PTA9	ADC0_SE2/ TSIO_IN0	ADC0_SE2/ TSIO_IN0	PTA9		
29	—	—	—	PTB20	DISABLED	DISABLED	PTB20		
30	—	—	—	VSS	VSS	VSS			
31	—	—	—	VDD	VDD	VDD			
32	—	—	—	PTB14/ IRQ_11	DISABLED	DISABLED	PTB14/ IRQ_11	EXTRG_IN	
33	21	21	—	PTA10/ IRQ_12	DISABLED	TSIO_IN11	PTA10/ IRQ_12		
34	22	22	—	PTA11/ IRQ_13	DISABLED	TSIO_IN10	PTA11/ IRQ_13		
35	23	23	17	PTB3/ IRQ_14	DISABLED	DISABLED	PTB3/ IRQ_14	I2C0_SCL	UART0_TX
36	24	24	18	PTB4/ IRQ_15/ LLWU_P6	DISABLED	DISABLED	PTB4/ IRQ_15/ LLWU_P6	I2C0_SDA	UART0_RX
37	25	25	19	PTB5/ IRQ_16	NMI_b	ADC0_SE1/ CMP0_IN1	PTB5/ IRQ_16	TPM1_CH1	NMI_b
38	26	26	20	PTA12/ IRQ_17/ LPTMR0_ALT2	ADC0_SE0/ CMP0_IN0	ADC0_SE0/ CMP0_IN0	PTA12/ IRQ_17/ LPTMR0_ALT2	TPM1_CH0	TPM_CLKIN0
39	27	27	—	PTA13	TSIO_IN9	TSIO_IN9	PTA13		
40	28	28	—	PTB12	TSIO_IN8	TSIO_IN8	PTB12		
41	—	—	—	PTA19	DISABLED	DISABLED	PTA19		SPI0_SS_b
42	—	—	—	PTB15	DISABLED	DISABLED	PTB15	SPI0_MOSI	SPI0_MISO
43	—	—	—	PTB16	DISABLED	DISABLED	PTB16	SPI0_MISO	SPI0_MOSI
44	—	—	—	PTB17	DISABLED	DISABLED	PTB17	TPM_CLKIN1	SPI0_SCK
45	29	29	21	PTB13	ADC0_SE13	ADC0_SE13	PTB13	TPM1_CH1	RTC_CLKOUT
46	30	30	22	PTA0/ IRQ_0/ LLWU_P7	SWD_CLK	ADC0_SE12/ CMP0_IN2	PTA0/ IRQ_0/ LLWU_P7	TPM1_CH0	SWD_CLK
47	31	31	23	PTA1/ IRQ_1/ LPTMR0_ALT1	RESET_b	DISABLED	PTA1/ IRQ_1/ LPTMR0_ALT1	TPM_CLKIN0	RESET_b
48	32	32	24	PTA2	SWD_DIO	DISABLED	PTA2	CMP0_OUT	SWD_DIO

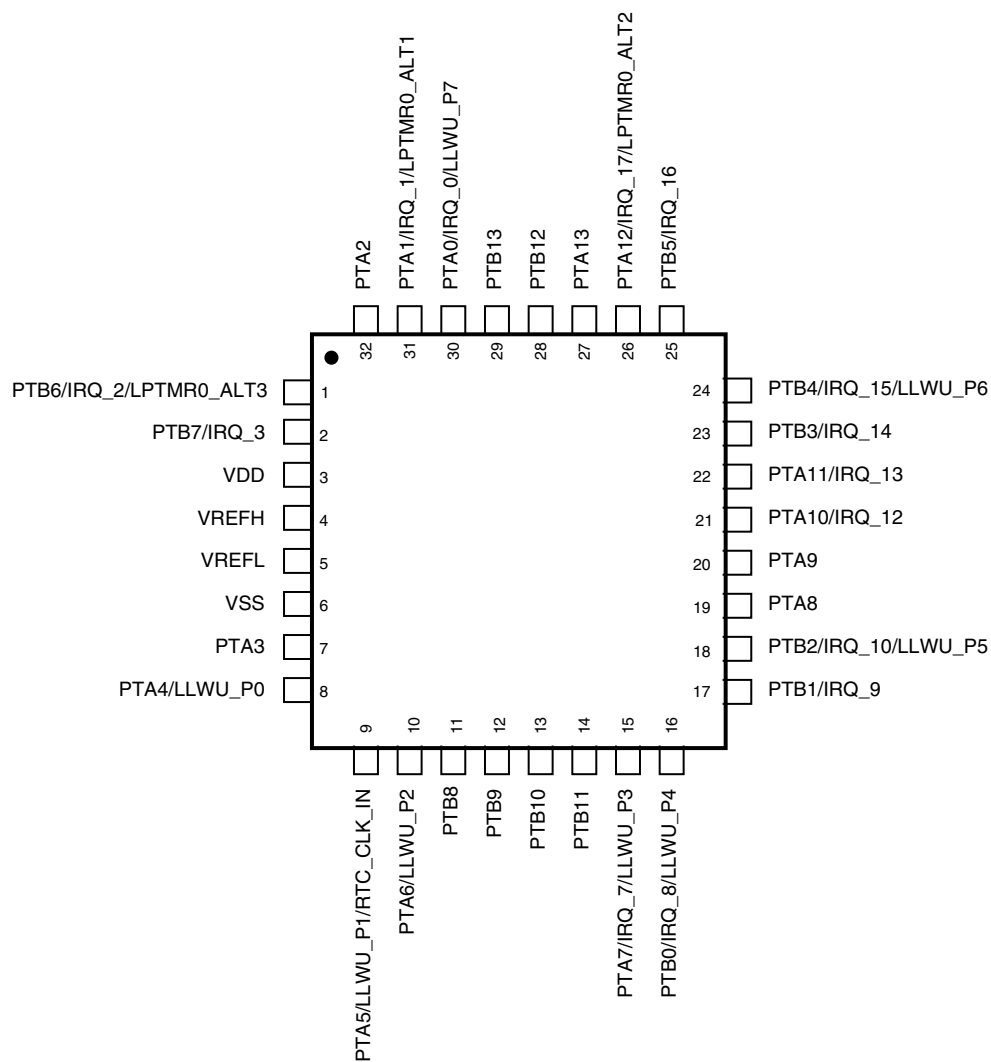


Figure 17. KL05 32-pin LQFP pinout diagram

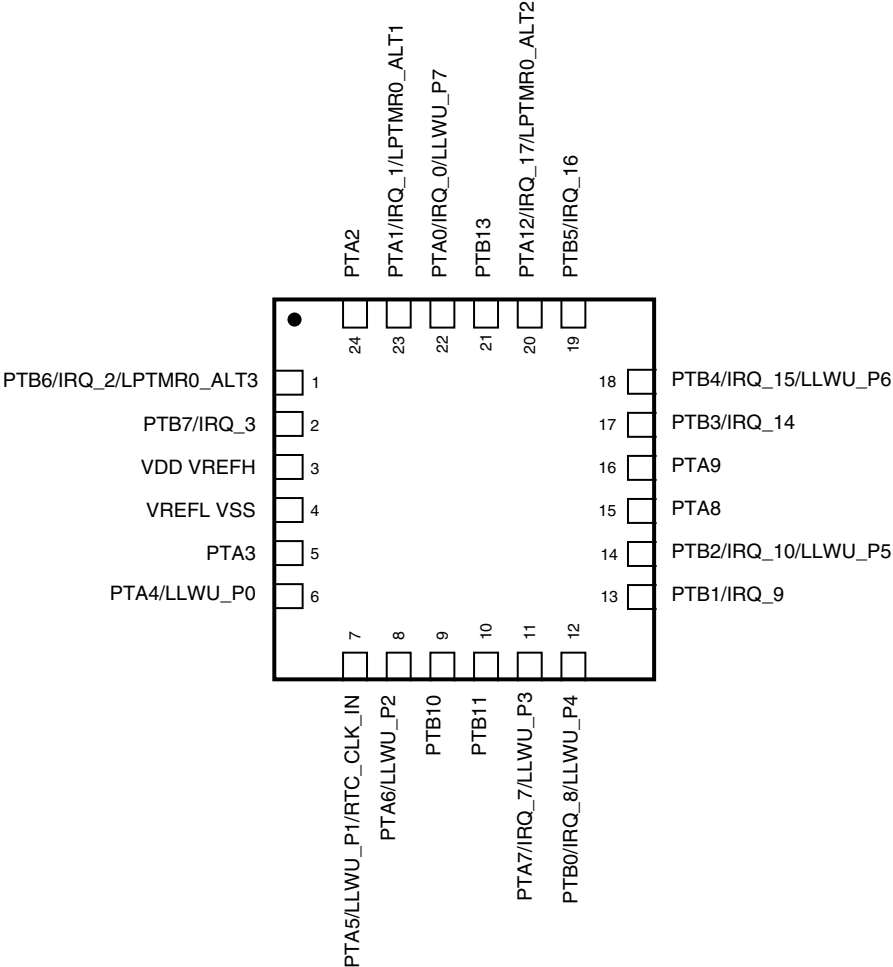


Figure 19. KL05 24-pin QFN pinout diagram

9 Revision History

The following table provides a revision history for this document.

Table 28. Revision History

Rev. No.	Date	Substantial Changes
1	7/2012	Initial NDA release.
2	9/2012	Initial public release.
3	11/2012	Completed all the TBDs.

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